



300mA, LOW QUIESCENT CURRENT, FAST TRANSIENT LOW DROPOUT LINEAR REGULATOR

Description

The AP7335A-50 is a 300mA, 5.0V fixed output voltage, low-dropout linear regulator with \pm 1% output voltage accuracy. The device includes pass element, error amplifier, band-gap, current limit and thermal shutdown circuitry. The device is turned on when EN pin is set to logic high level.

The characteristics of low-dropout voltage and low-quiescent current make it suitable for low-power applications, for example, battery powered devices. The typical quiescent current is 35μ A. Built-in, current-limit and thermal-shutdown functions prevent IC from damage in fault conditions.

This device is only available as a 5.0V fixed version. Please contact your local sales office for any other voltage options.

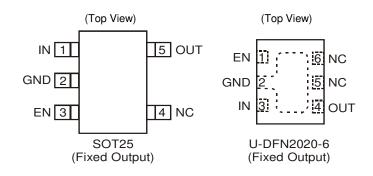
The AP7335A-50 is packaged in SOT25 and U-DFN2020-6.

Features

.

- 300mA Low Dropout Regulator with EN
- Very Low I_Q 35μA
- Fixed Output at 5.0V
 - V_{IN(MIN)} 5.5V
- High PSRR: 65dB at 1kHz
- Fast Start-up Time 220µs
- Stable with Low ESR, 1µF Ceramic Output Capacitor
- Excellent Load/Line Transient Response
- Low Dropout 150mV at 300mA
- Current Limit and Short Circuit Protection
- Thermal Shutdown Protection
- Ambient Temperature Range -40°C to +85°C
- SOT25, and U-DFN2020-6 Available in "Green" Molding Compound (No Br, Sb)
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Pin Assignments



Applications

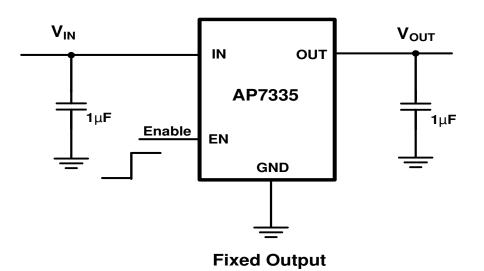
- Smart Phones
- MP3/MP4s
- Battery-Powered Devices
- Bluetooth Headsets
- Battery Chargers
- LCD TVs
- Multifunction Monitors

Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.

- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 - 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds



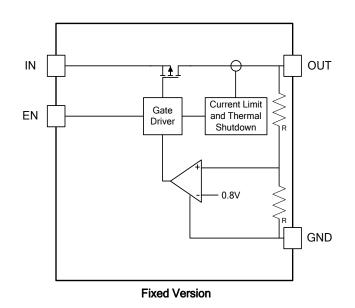
Typical Applications Circuit



Pin Descriptions

	Package Name		
Pin Number	SOT25 (Fixed)	U-DFN2020-6 (Fixed)	Function
IN	1	3	Voltage input pin. Bypass to ground through at least $1\mu F$ MLCC capacitor
GND	2	2	Ground
EN	3	1	Enable input, active high
NC	4	5, 6	No connection
OUT	5	4	Voltage output pin. Bypass to ground through 1µF MLCC capacitor

Functional Block Diagram



NEW PRODUCT



Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.) (Note 4)

Symbol	Parameter	Rating	Unit
V _{IN}	Input Voltage	6.5	V
V _{OUT} , V _{EN}	OUT, EN Voltage	V _{IN} + 0.3	V
ILIMIT	Continuous Load Current per Channel	Internal Limited	mA
T _{ST}	Storage Temperature Range	-65 to +150	°C
ESD HBM	Human Body Model ESD Protection	2,000	V
ESD MM	Machine Model ESD Protection	200	V

Note: 4. Stresses greater than the 'Absolute Maximum Ratings' specified above, may cause permanent damage to the device. These are stress ratings only; functional operation of the device at these or any other conditions exceeding those indicated in this specification is not implied. Device reliability may be affected by exposure to absolute maximum rating conditions for extended periods of time.

Recommended Operating Conditions (@T_A = +25°C, unless otherwise specified.)

Symbol	Parameter	Min	Мах	Unit
V _{IN}	Input voltage (Note 6)	5.5 (Note 6)	6	V
Ιουτ	Output Current (Note 5)	0	300	mA
T _A	Operating Ambient Temperature	-40	+85	°C

Notes: 5. The device maintains a stable, regulated output voltage without a load current.

6. $V_{IN(MIN)} = 5.5V$ for 5.0V, V_{OUT} at 300mA lout.



Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

(T_A = +25°C, V_{IN} = 5.5 to 6V, C_{IN} = 1 μ F, C_{OUT} = 1 μ F, V_{EN} = 2V, unless otherwise stated)

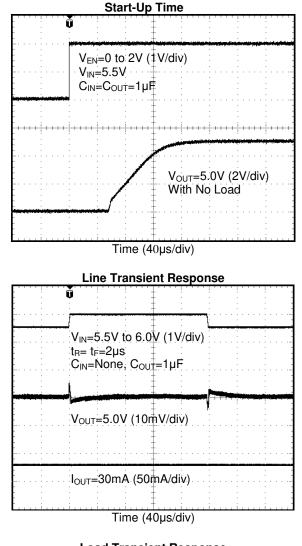
Symbol	Parameter	Test Conditions	Min	Тур.	Max	Unit
		$T_{A} = -40^{\circ}C \text{ to } +85^{\circ}C,$	-1		1	%
V _{OUT}	Output Voltage Accuracy	I _{OUT} = 10% of I _{OUT-Max}	-1	-		
ΔV_{OUT}	Line Degulation	$V_{IN} = 5.5V$ to 6V,	_	0.02	0.20	%/V
$\Delta V_{\text{IN}}/V_{\text{OUT}}$	Line Regulation	$V_{EN} = V_{IN}, I_{OUT} = 1mA$	-	0.02	0.20	%)/V
ΔV_{OUT}	Load Regulation	$V_{IN} = 5.5V$ to 6V,	-0.6		0.0	%
/V _{OUT}		$I_{OUT} = 1$ mA to 300mA	-0.6	-	0.6	70
VDROPOUT	Dropout Voltage (Note 7)	I _{OUT} = 300mA	-	150	200	mV
la	Input Quiescent Current	$V_{EN} = V_{IN}, I_{OUT} = 0mA$	-	35	80	μA
I _{SHDN}	Input Shutdown Current	$V_{EN} = 0V, I_{OUT} = 0mA$	-	0.1	1	μA
I _{LEAK}	Input Leakage Current	V _{EN} = 0V, OUT Grounded	-	0.1	1	μA
Ŧ	Start-up Time	$V_{EN} = 0V$ to 2.0V in 1µs,		220	-	μs
T _{ST}		I _{OUT} = 300mA	-			
DODD		$V_{IN} = 5.5 V_{DC} + 0.5 V_{PPAC},$		65	-	dB
PSRR	PSRR	$f = 1 kHz$, $I_{OUT} = 50 mA$	-			
1	Oh and a low it Original	$V_{IN} = V_{IN-Min}$ to V_{IN-Max} ,		100		mA
ISHORT	Short-circuit Current	$V_{OUT} < 0.2V$ (Fixed)	-	160	-	
L	Current limit	$V_{IN} = V_{IN-Min}$ to V_{IN-Max} ,	400	650	-	mA
ILIMIT		$V_{OUT}/R_{OUT} = 1.2A$	400	650		
V _{IL}	En Input Logic Low Voltage	$V_{IN} = V_{IN-Min}$ to V_{IN-Max}	-	-	0.4	V
VIH	En Input Logic High Voltage	$V_{IN} = V_{IN-Min}$ to V_{IN-Max}	1.4	-		V
I _{EN}	En Input Current	$V_{IN} = 0V \text{ or } V_{IN-Max}$	-1	-	1	μA
T _{SHDN}	Thermal Shutdown Threshold	-	-	+145	-	°C
T _{HYS}	Thermal Shutdown Hysteresis	-	-	+15	-	°C
		SOT25 (Note 8)	-	- 187	-	
θ _{JA}	Thermal Resistance Junction-to-Ambient	U-DFN2020-6 (Note 8)	-	251	-	°C/W

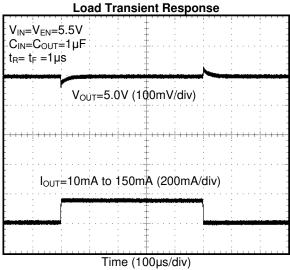
Notes:

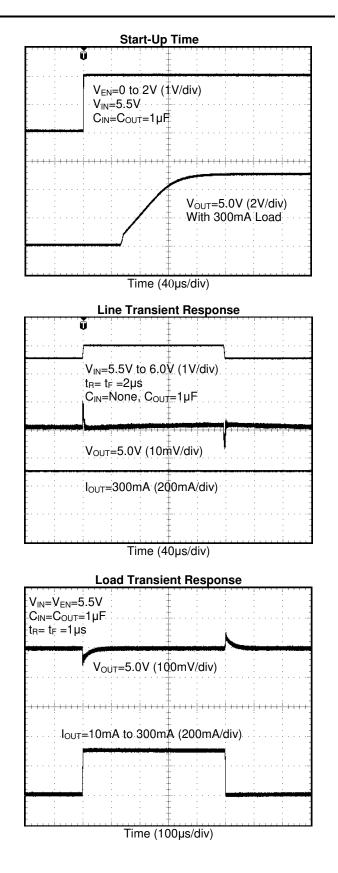
7. Dropout voltage is the voltage difference between the input and the output at which the output voltage drops 2% below its nominal value.
8. Test condition for all packages: Device mounted on FR-4 substrate PC board, 1oz copper, with minimum recommended pad layout.



Performance Characteristics

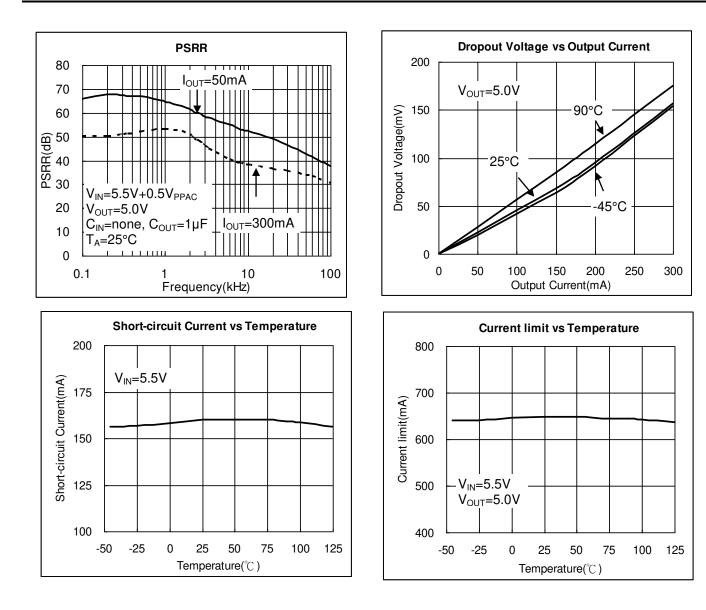








Performance Characteristics (Cont.)



AP7335A-50 Document number: DS38527 Rev. 1 - 2



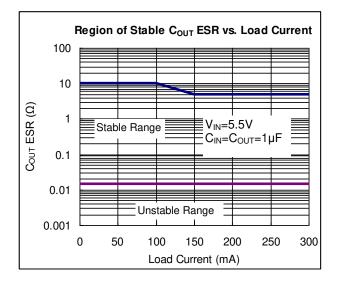
Application Note

Input Capacitor

A 1µF ceramic capacitor is recommended between IN and GND pins to decouple input power supply glitch and noise. The amount of the capacitance may be increased without limit. This input capacitor must be located as close as possible to the device to assure input stability and reduce noise. For PCB layout, a wide copper trace is required for both IN and GND pins. A lower ESR capacitor type allows the use of less capacitance, while higher ESR type requires more capacitance.

Output Capacitor

The output capacitor is required to stabilize and improve the transient response of the LDO. The AP7335A-50 is stable with very small ceramic output capacitors. Using a ceramic capacitor value that is at least 1μ F with ESR > $15m\Omega$ on the output ensures stability. Higher capacitance values help to improve line and load transient response. The output capacitance may be increased to keep low undershoot and overshoot. Output capacitor must be placed as close as possible to OUT and GND pins.



No Load Stability

No minimum load is required to keep the device stable. The device will remain stable and regulated in no load condition.

ON/OFF Input Operation

The AP7335A-50 is turned on by setting the EN pin high, and is turned off by pulling it low. If this feature is not used, the EN pin should be tied to IN pin to keep the regulator output on at all time. To ensure proper operation, the signal source used to drive the EN pin must be able to swing above and below the specified turn-on/off voltage thresholds listed in the Electrical Characteristics section under V_{IL} and V_{IH} .

Current Limit Protection

When output current at OUT pin is higher than current limit threshold, the current limit protection will be triggered and clamp the output current to approximately 650mA to prevent overcurrent and to protect the regulator from damage due to overheating.

Short Circuit Protection

When OUT pin is short-circuit to GND, short circuit protection will be triggered and clamp the output current to approximately 160mA. This feature protects the regulator from overcurrent and damage due to overheating.

Thermal Shutdown Protection

Thermal protection disables the output when the junction temperature rises to approximately +145°C, allowing the device to cool down. When the junction temperature reduces to approximately +130°C the output circuitry is enabled again. Depending on power dissipation, thermal resistance, and ambient temperature, the thermal protection circuit may cycle on and off. This cycling limits the heat dissipation of the regulator, protecting it from damage due to overheating.

Ultra Fast Start-Up

After enabled, the AP7335A-50 is able to provide full power in as little as tens of microseconds, typically 220µs, without sacrificing low ground current. This feature will help load circuitry move in and out of standby mode in real time, eventually extend battery life for mobile phones and other portable devices.



Application Note

Fast Transient Response

Fast transient response LDO can extend battery life. TDMA-based cell phone protocols such as Global System for Mobile Communications (GSM) have a transmit/receive duty factor of only 12.5 percent, enabling power savings by putting much of the baseband circuitry into standby mode in between transmit cycles. In baseband circuits, the load often transitions virtually instantaneously from 100µA to 100mA. To meet this load requirement, the LDO must react very quickly without a large voltage drop or overshoot — a requirement that cannot be met with conventional, general-purpose LDO.

The AP7335A-50's fast transient response from 0 to 300mA provides stable voltage supply for fast DSP and GSM chipset with fast changing load.

Low Quiescent Current

The AP7335A-50, consuming only around 35µA for all input range, provides great power saving in portable and low power applications.

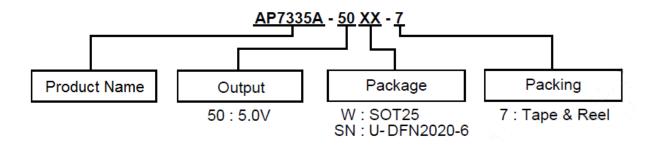
Power Dissipation

The device power dissipation and proper sizing of the thermal plane that is connected to the thermal pad is critical to avoid thermal shutdown and ensure reliable operation. Power dissipation of the device depends on input voltage and load conditions and can be calculated by:

The maximum power dissipation, handled by the device, depends on the maximum junction to ambient thermal resistance, maximum ambient temperature, and maximum device junction temperature, which can be calculated by the following equation:

$$P_{D}(max@T_{A}) = \frac{(+145^{\circ}C - T_{A})}{R_{\theta}JA}$$

Ordering Information



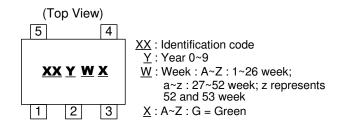
Davias	Deekene Oede	Packaging	7" Tape a	and Reel	
Device	Device Package Code		Quantity	Part Number Suffix	
AP7335A-50W-7	W	SOT25	3,000/Tape & Reel	-7	
AP7335A-50SN-7	SN	U-DFN2020-6	3,000/Tape & Reel	-7	

Note: 9. Pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.



Marking Information

(1) SOT25



Device	Package	Identification Code
AP7335A-50W-7	SOT25	ТР

(2) U-DFN2020-6

(Top View)



 $\begin{array}{l} \underline{XX}: \text{Identification Code} \\ \underline{Y}: \text{Year}: 0~9 \\ \underline{W}: \text{Week}: A~Z: 1~26 \text{ week}; \\ a~z: 27~52 \text{ week}; z \text{ represents} \\ 52 \text{ and } 53 \text{ week} \\ \underline{X}: A~Z: G = Green \end{array}$

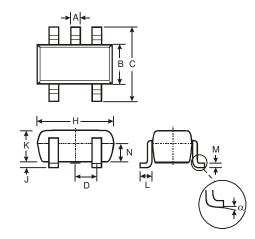
Device	Package	Identification Code	
AP7335A-50SN-7	U-DFN2020-6	TP	



Package Outline Dimensions (All dimensions in mm.)

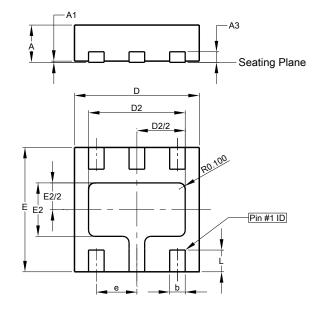
Please see http://www.diodes.com/package-outlines.html for the latest version.

(1) Package Type: SOT25



	SOT25				
Dim	Min	Max	Тур		
Α	0.35	0.50	0.38		
В	1.50	1.70	1.60		
С	2.70	3.00	2.80		
D	_	—	0.95		
н	2.90	3.10	3.00		
J	0.013	0.10	0.05		
К	1.00	1.30	1.10		
L	0.35	0.55	0.40		
М	0.10	0.20	0.15		
Ν	0.70	0.80	0.75		
α	0°	8°	_		
All D	All Dimensions in mm				

(2) Package Type: U-DFN2020-6



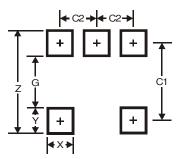
	U-DFN2020-6				
Dim	Min	Max	Тур		
Α	0.57	0.63	0.60		
A1	0	0.05	0.03		
A3	-	-	0.15		
b	0.20	0.30	0.25		
D	1.95	2.075	2.00		
D2	1.45	1.65	1.55		
е	-	-	0.65		
Е	1.95	2.075	2.00		
E2	0.76	0.96	0.86		
L	0.30	0.40	0.35		
	All Dimensions in mm				



Suggested Pad Layout

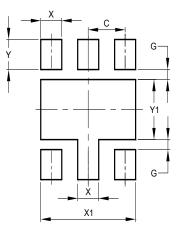
Please see http://www.diodes.com/package-outlines.html for the latest version.

(1) Package Type: SOT25



Dimensions	Value (in mm)
Z	3.20
G	1.60
Х	0.55
Y	0.80
C1	2.40
C2	0.95

(2) Package Type: U-DFN2020-6

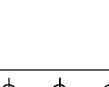


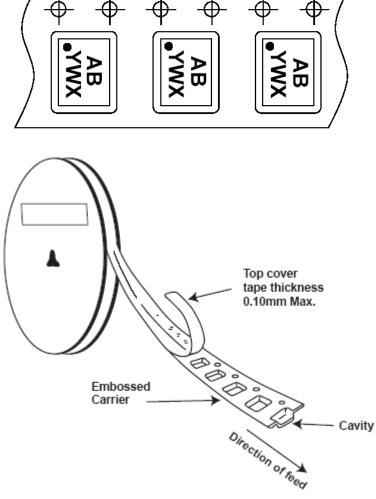
Dimensions	Value
Dimensions	(in mm)
С	0.65
G	0.15
Х	0.37
X1	1.67
Y	0.45
Y1	0.90



Taping Orientation (Note 10)

For U-DFN2020-6









IMPORTANT NOTICE

DIODES INCORPORATED MAKES NO WARRANTY OF ANY KIND, EXPRESS OR IMPLIED, WITH REGARDS TO THIS DOCUMENT, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION).

Diodes Incorporated and its subsidiaries reserve the right to make modifications, enhancements, improvements, corrections or other changes without further notice to this document and any product described herein. Diodes Incorporated does not assume any liability arising out of the application or use of this document or any product described herein; neither does Diodes Incorporated convey any license under its patent or trademark rights, nor the rights of others. Any Customer or user of this document or products described herein in such applications shall assume all risks of such use and will agree to hold Diodes Incorporated and all the companies whose products are represented on Diodes Incorporated website, harmless against all damages.

Diodes Incorporated does not warrant or accept any liability whatsoever in respect of any products purchased through unauthorized sales channel. Should Customers purchase or use Diodes Incorporated products for any unintended or unauthorized application, Customers shall indemnify and hold Diodes Incorporated and its representatives harmless against all claims, damages, expenses, and attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized application.

Products described herein may be covered by one or more United States, international or foreign patents pending. Product names and markings noted herein may also be covered by one or more United States, international or foreign trademarks.

This document is written in English but may be translated into multiple languages for reference. Only the English version of this document is the final and determinative format released by Diodes Incorporated.

LIFE SUPPORT

Diodes Incorporated products are specifically not authorized for use as critical components in life support devices or systems without the express written approval of the Chief Executive Officer of Diodes Incorporated. As used herein:

- A. Life support devices or systems are devices or systems which:
 - 1. are intended to implant into the body, or
 - 2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.
- B. A critical component is any component in a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or to affect its safety or effectiveness.

Customers represent that they have all necessary expertise in the safety and regulatory ramifications of their life support devices or systems, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of Diodes Incorporated products in such safety-critical, life support devices or systems, notwithstanding any devices- or systems-related information or support that may be provided by Diodes Incorporated. Further, Customers must fully indemnify Diodes Incorporated and its representatives against any damages arising out of the use of Diodes Incorporated products in such safety-critical, life support devices or systems.

Copyright © 2016, Diodes Incorporated

www.diodes.com